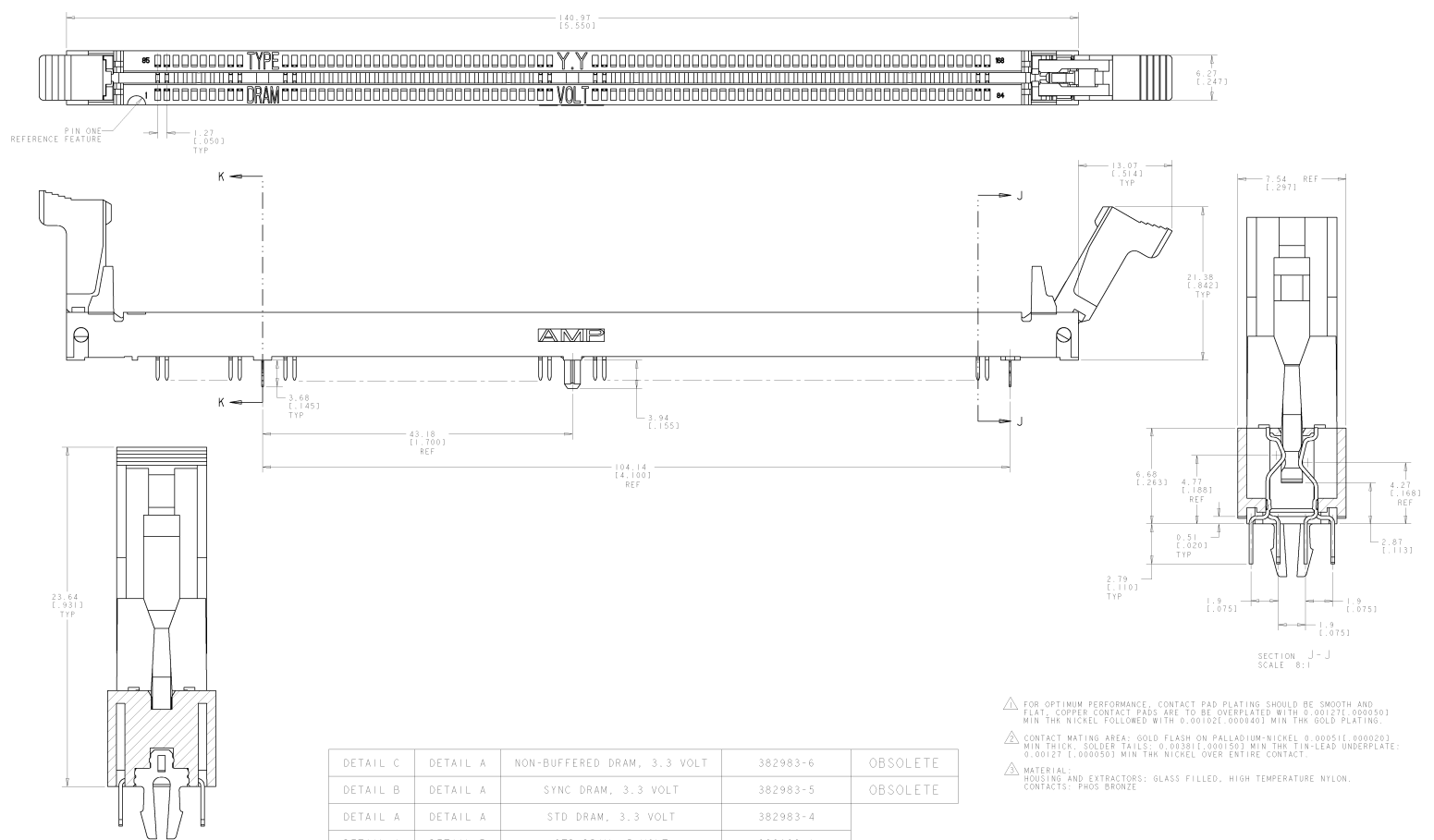


REV	DATE	DESCRIPTION	BY	CHK	APP
B	04-01-91	REVISED PER 04-01-91	UNWIN	AM	DS
C	02-01-93	REVISED PER 02-01-93	UNWIN	AM	DS
D	05-20-93	REVISED PER 05-20-93	UNWIN	AM	DS
E	05-10-94	REVISED PER 05-10-94	UNWIN	AM	DS



DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	382983-6	OBSOLETE
DETAIL B	DETAIL A	SYNC DRAM, 3.3 VOLT	382983-5	OBSOLETE
DETAIL A	DETAIL A	STD DRAM, 3.3 VOLT	382983-4	
DETAIL A	DETAIL B	STD DRAM, 5 VOLT	382983-1	
KEY #1	KEY #2	PART DESCRIPTION	PART NUMBER	

⚠ FOR OPTIMUM PERFORMANCE, CONTACT PAD PLATING SHOULD BE SMOOTH AND FLAT. COPPER CONTACT PADS ARE TO BE OVERPLATED WITH 0.00127 (0.00050) MIN THK NICKEL FOLLOWED WITH 0.00102 (0.00040) MIN THK GOLD PLATING.

⚠ CONTACT MATING AREA: GOLD FLASH ON PALLADIUM-NICKEL 0.00051 (0.00020) MIN THICK. SOLDER TAILS: 0.08381 (0.00330) MIN THK TIN-LEAD UNDERPLATE: 0.00127 (0.00050) MIN THK NICKEL OVER ENTIRE CONTACT.

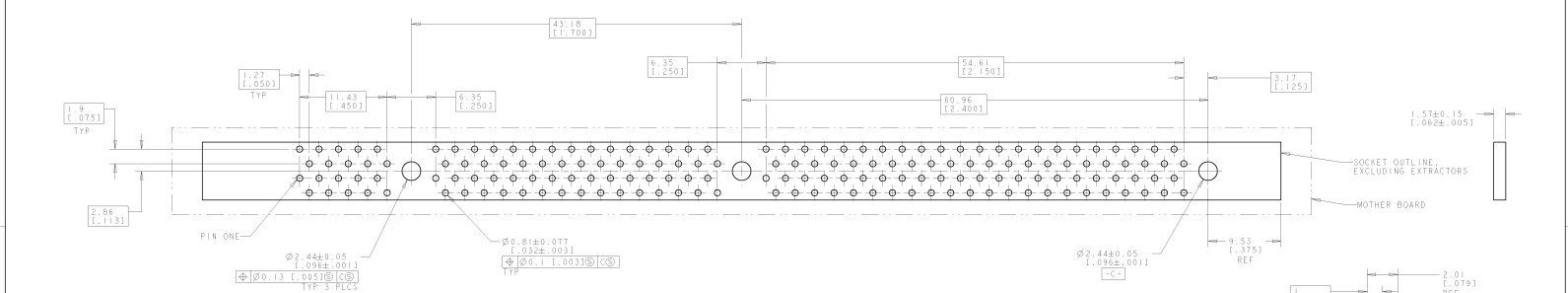
⚠ MATERIAL: HOUSING AND EXTRACTORS: GLASS FILLED, HIGH TEMPERATURE NYLON. CONTACTS: PHOS BRONZE

SECTION K-K
SCALE 8:1

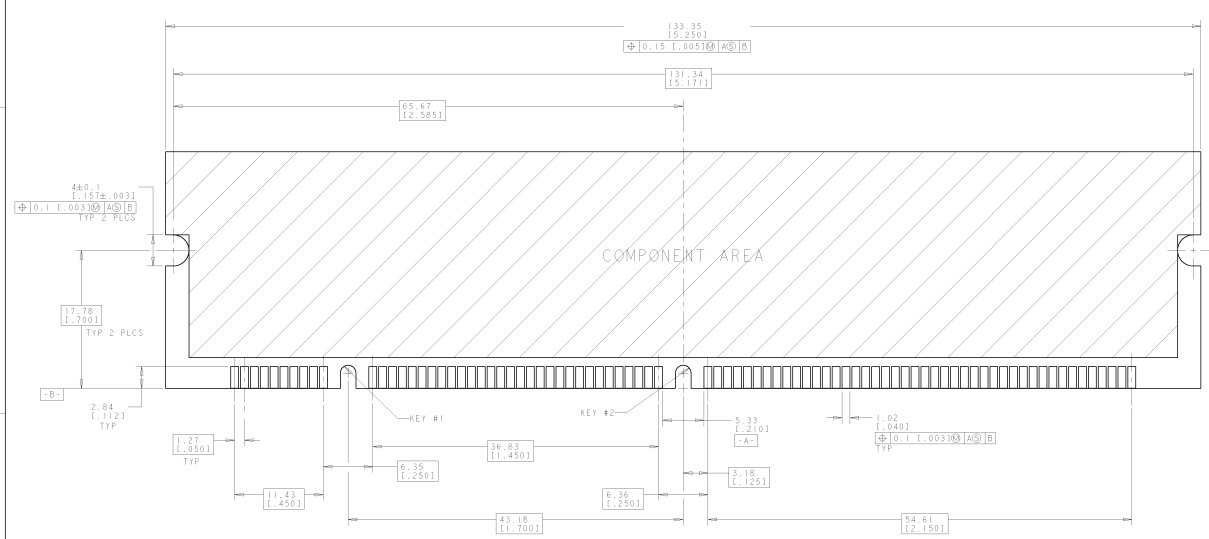
SECTION J-J
SCALE 8:1

MICROELECTRONIC COMPONENTS DIVISION AMP CORPORATION 200 SOUTH BRIDGE STREET WILMINGTON, MA 01890-1000		DATE: 25-APR-93 DRAWN BY: S. HILLEY CHECKED BY: S. HILLEY APPROVED BY: S. HILLEY		AMP MICROELECTRONIC COMPONENTS DIVISION WILMINGTON, MA 01890-1000	
TITLE: SOCKET ASSY, DUAL READ-OUT, VERSION 11, 8 BYTE, 108 POSITION		PART NO: A1 00779		DRAWING NO: C-382983	
MATERIAL:		FINISH:		CUSTOMER DRAWING:	

REV	DATE	BY	CHKD	REVISIONS
AG	53			
				SEE SHEET 1

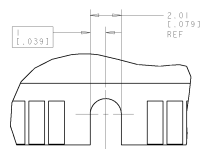


RECOMMENDED CIRCUIT BOARD HOLE LAYOUT

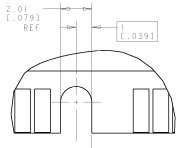


RECOMMENDED MODULE LAYOUT

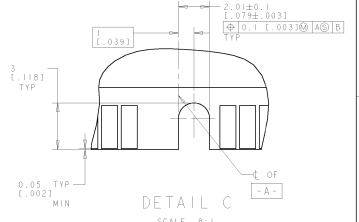
SEE JEDEC SPEC. MO-161 FOR COMPLETE MODULE DETAILS
1.27±0.10(±0.05±0.004) THICK ACROSS CONTACT PADS



DETAIL A
SCALE 8:1



DETAIL B
SCALE 8:1



DETAIL C
SCALE 8:1

AMP AMP CORPORATION 1000 MARKET STREET PHILADELPHIA, PA 19104-1000	
DATE: 25-APR-95 BY: J. HALL FOR: AMP	AMP SOCKET ASSY, DUAL READ-OUT, VERSION 11-B BYTE, 1GB POSITION
MATERIAL: SEE SH 1	TITLE: 00779 PART: 382983